Standex Electronics
PARTNER | SOLVE | DELIVER®

3D IMAGING CAPABILITIES DESIGN, VALIDATION & QUALITY

MICROFOCUS X-RAY IMAGING

NON-DESTRUCTIVE, HIGH RESOLUTION X-RAY SCREENING

- ✓ Yxlon's Y. Cougar microfocus X-ray machine is a specialty high-magnification imaging system that has recently been added to our laboratory capabilities.
- ✓ Rated for non-destructive testing applications and quality assurance performance.
- ✓ Inspection of internal details of encapsulated, hidden, and sealed components and assemblies with 2D/3D imagery, CT scans.
- ✓ Valuable for many markets and applications including Automotive, Mil-Aero, Telecommunications, Medical, Aviation, HVAC/R, Test & Measurement, and more.

VALUE AND BENEFITS

- › A differentiating development tool for custom component and assembly development and validation activities.
- › Improves delivered quality, reduces downtime, and return merchandise authorizations (RMA's) by enabling advanced part screening capabilities for larger production runs.
- › Non-destructive, high-resolution X-ray of parts for quality assurance, 2D, 3D, and CT scan imagery allowing for inspection of encapsulated internal details.
- › Provides a superior failure analysis capability to expedite problem resolution and ensure corrective action effectiveness.
- › Functionality allows for remote viewing & screening online by customers, and off-premise plants. Not on-site. No worries!

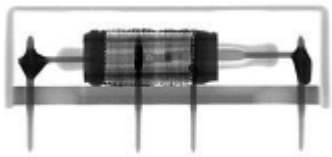

Figure 1.

Figure 2.

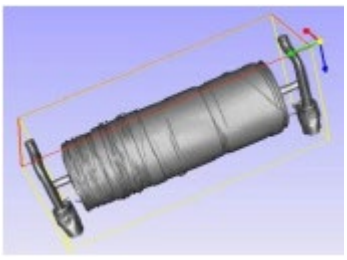

Figure 3.

2D ANALYSIS

› *Figure 1.* X-ray of an LI series reed relay measuring 30mmx10mmx10.4mm. Scans can detect construction details such as solder connections, winding build, and lead routing with 2D/3D scans throughout even the smallest of relays.

› *Figure 2.* X-ray of MILPRF27 Grade 5, encapsulated toroidal transformer with multiple windings measuring 35mm in diameter.2D and 3D scans enable inspection and non-destructive failure analysis.

3D ANALYSIS

› *Figure 3.* Quality Assurance, Non-Destructive Failure Analysis, Evaluate Difficult to Penetrate Materials, Deep Root Cause Analysis and Accuracy, Detect Foreign Objects and Debris, View Windings, Terminals, and Joints in Detail

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